# UNHZ204

## Circuit Protector Elements

For overcurrent protection

### ■ Features

- Sharp cutoff characteristics and low voltage drop
- Flame retardant package and low heat generation, high density mounting is possible.

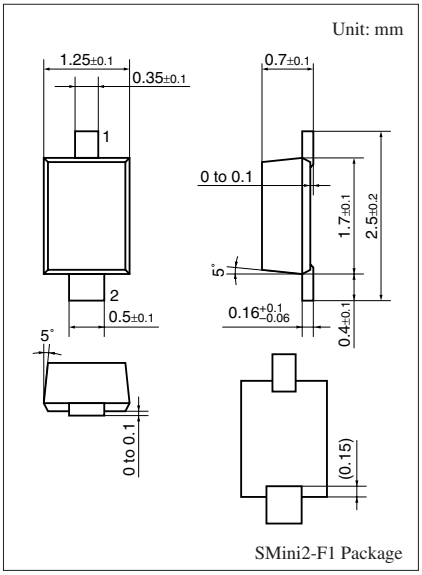
### ■ Absolute Maximum Ratings $T_a = 25°C$

| Parameter | Symbol | Rating | Unit |
|---|---|---|---|
| Operating ambient temperature | $T_{opr}$ | −55 to +125 | °C |
| Storage temperature | $T_{stg}$ | −55 to +125 | °C |

### ■ Electrical Characteristics $T_a = 25°C \pm 3°C$

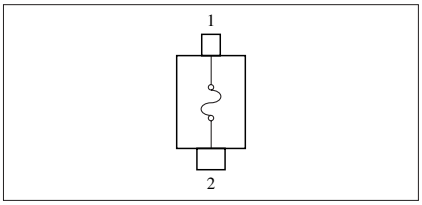
| Parameter | Min | Typ | Max | Unit |
|---|---|---|---|---|
| Rated voltage | | 50 | | V |
| Rated current | | 1.5 | | A |
| Internal Resistance | 27 | 35 | 43 | mΩ |
| Cutoff current * | | 3.0 | | A |

Note) ∗: Measurement condition of cutoff current shall be at $T_a = 25°C$, t = 1 s
Tolerance of cutoff current shall be ± 20%




Marking Symbol: H4

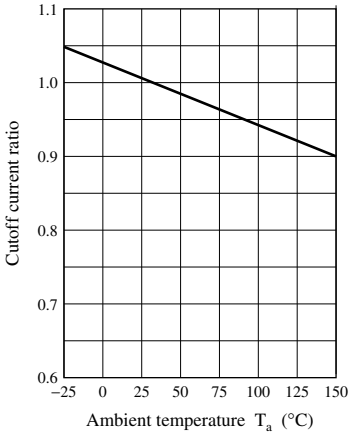
Lead Connection



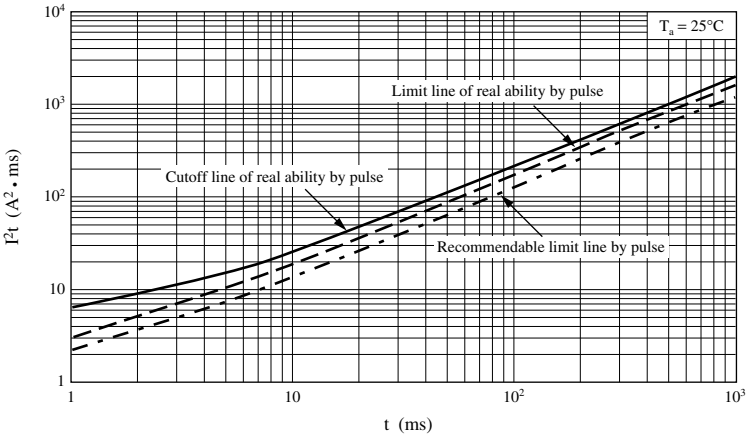

### ■ Usage Notes

- Package shall be overheated and dangerous for overcurrent.
- This device should be used only to the secondary circuit.
  Package will be damaged for added overpower.
- This device is not electrical fuse legally. Please draw a clear line between electrical fuse from this device.

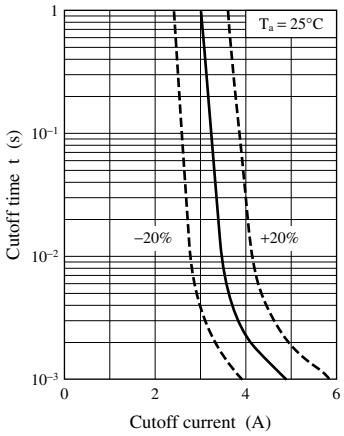
Cutoff current ratio — $T_a$




$I^2t$ — t




Cutoff current characteristics



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